



DCR470G85

Phase Control Thyristor

DS5894-5 January 2014 (LN31215)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V _{DRM} and V _{RRM} V	Conditions
DCR470G85* DCR470G80 DCR470G70	8500 8000 7000	$\begin{split} T_{vj} &= \text{-}40^{\circ}\text{C to 125}^{\circ}\text{C}, \\ I_{DRM} &= I_{RRM} = 100\text{mA}, \\ V_{DRM}, V_{RRM}t_p &= 10\text{ms}, \\ V_{DSM}\&V_{RSM} &= \\ V_{DRM}\&V_{RRM} + 100V \\ respectively \end{split}$

Lower voltage grades available. *8200V @ -40°C, 8500V @ 0°C

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR470G85

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

V_{DRM}	8500V
I _{T(AV)}	467A
I _{TSM}	5250A
dV/dt*	1500V/μs
dl/dt	200A/us

* Higher dV/dt selections available

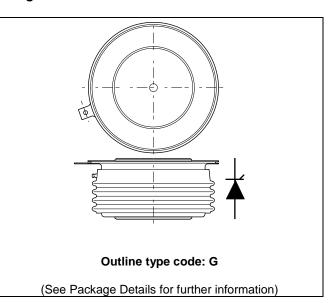


Fig. 1 Package outline



CURRENT RATINGS

$T_{case} = 60$ °C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Side Cooled				
I _{T(AV)}	Mean on-state current	Half wave resistive load	467	А
I _{T(RMS)}	RMS value	-	734	А
I _T	Continuous (direct) on-state current	-	725	А

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I _{TSM}	Surge (non-repetitive) on-state current	10ms half sine, T _{case} = 125°C	5.25	kA
l ² t	I ² t for fusing	$V_R = 0$	0.138	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R _{th(j-c)}	Thermal resistance – junction to case	Double side cooled DC		-	0.0268	°C/W
		Single side cooled Anode DC		-	0.0527	°C/W
		Cathode DC		-	0.0652	°C/W
R _{th(c-h)}	Thermal resistance – case to heatsink	Clamping force 11.5kN Double side		-	0.0072	°C/W
		(with mounting compound) Single side		-	.0144	°C/W
T_{vj}	Virtual junction temperature	Blocking V _{DRM} / _{VRRM}		-	125	°C
T _{stg}	Storage temperature range			-55	125	°C
F _m	Clamping force			10	13	kN





DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I _{RRM} /I _{DRM}	Peak reverse and off-state current	At V _{RRM} /V _{DRM} , T _{case} = 125°C		-	100	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V_{DRM} , $T_j = 125$ °C, ga	ite open	-	1500	V/µs
dl/dt	Rate of rise of on-state current	From 67% V _{DRM} to 2x I _{T(AV)}	Repetitive 50Hz	-	100	A/µs
		Gate source 30V, 10Ω,	Non-repetitive	-	200	A/µs
		$t_r < 0.5 \mu s, T_j = 125 ^{\circ} C$				
V _{T(TO)}	Threshold voltage – Low level	50A to 400A at T _{case} = 125°C		-	1.162	V
	Threshold voltage – High level	400A to 1600A at T _{case} = 125°C		-	1.3063	V
r _T	On-state slope resistance – Low level	50A to 400A at T _{case} = 125°C		-	3.153	mΩ
	On-state slope resistance – High level	400A to 1600A at T _{case} = 125°C		-	2.763	mΩ
t _{gd}	Delay time	$V_D = 67\% \ V_{DRM}$, gate source 30V, 10Ω		-	3	μs
		$t_r = 0.5 \mu s$, $T_j = 25^{\circ}C$				
tq	Turn-off time	$T_j = 125$ °C, $V_R = 100$ V, $dI/dt = 100$ V	= 5A/µs,	-	1200	μs
		dV _{DR} /dt = 20V/μs linear				
Q _S	Stored charge	$I_T = 500A$, $T_j = 125$ °C, $dI/dt = 5A/\mu s$,		2000	3000	μC
IL	Latching current	$T_j = 25^{\circ}C, V_D = 5V$		-	3	Α
I _H	Holding current	$T_j = 25^{\circ}C, R_{G-K} = \infty, I_{TM} = 500$	0A, I _T = 5A	-	300	mA



GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	$V_{DRM} = 5V$, $T_{case} = 25$ °C	1.5	V
V_{GD}	Gate non-trigger voltage	At 50% V _{DRM} , T _{case} = 125°C	0.4	V
I _{GT}	Gate trigger current	V _{DRM} = 5V, T _{case} = 25°C	350	mA
I _{GD}	Gate non-trigger current	At 50% V _{DRM} , T _{case} = 125°C	10	mA

CURVES

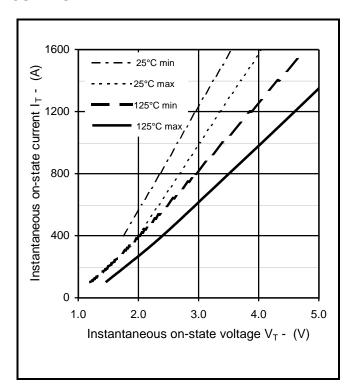


Fig.2 Maximum & minimum on-state characteristics

 $\begin{array}{lll} \textbf{V}_{\text{TM}} \; \textbf{EQUATION} & \text{Where} & \text{A} = 1.545561 \\ \text{B} = -0.202735 \\ \text{V}_{\text{TM}} = \text{A} + \text{BIn} \; (\textbf{I}_{\text{T}}) + \text{C}.\textbf{I}_{\text{T}} + \text{D}.\sqrt{\textbf{I}_{\text{T}}} & \text{C} = 0.001865 \\ \text{D} = 0.066158 \end{array}$

these values are valid for $T_j = 125$ °C for $I_T 50$ A to 1600A



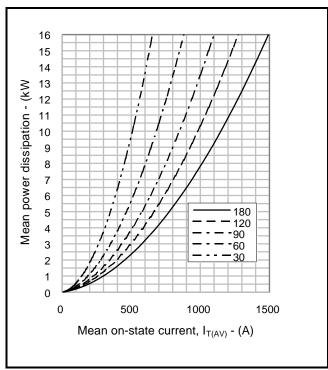


Fig.3 On-state power dissipation - sine wave

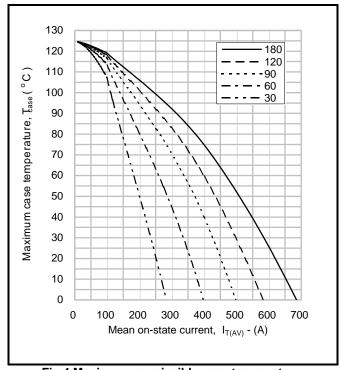


Fig.4 Maximum permissible case temperature, double side cooled – sine wave

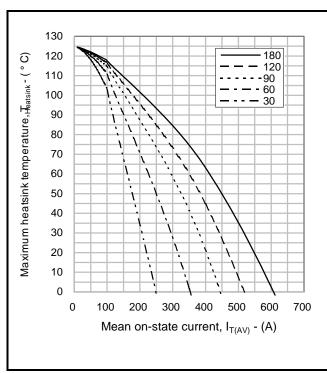


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

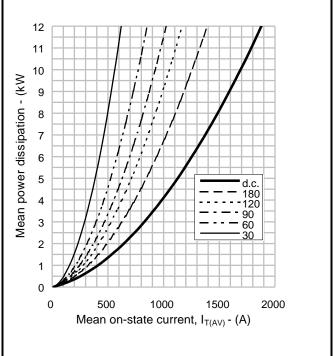


Fig.6 On-state power dissipation - rectangular wave

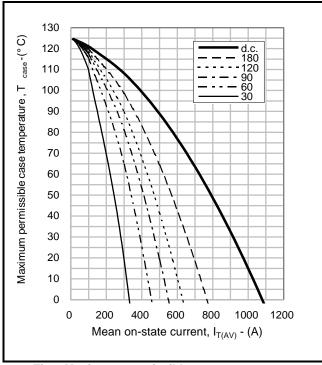


Fig.7 Maximum permissible case temperature, double side cooled - rectangular wave

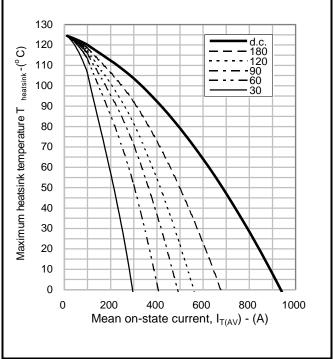
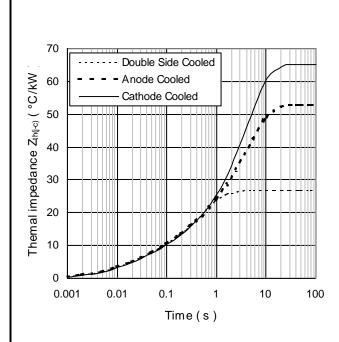


Fig.8 Maximum permissible heatsink temperature, double side cooled - rectangular wave



		1	2	3	4
Double side cooled	R _i (°C/kW)	2.2995	5.4226	16.9074	2.1488
	T _i (s)	0.0066401	0.0457025	0.4962482	1.8248
Anode side cooled	R _i (°C/kW)	2.3214	5.2661	10.2686	34.8031
	T _i (s)	0.0066948	0.045528	0.3484209	4.582
Cathode side cooled	R _i (°C/kW)	2.4895	5.9105	7.4256	49.3432
	T _i (s)	0.0070404	0.052895	0.3933903	4.2295

 $Z_{th} = \sum [R_i x (1-exp. (t/t_i))]$ [1]

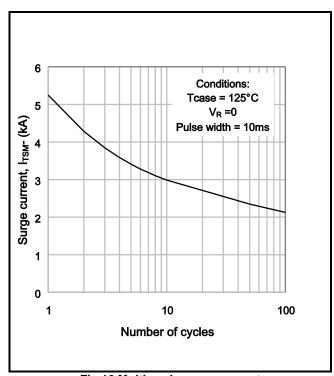
 $\Delta R_{\text{th(j-c)}}$ Conduction

Tables show the increments of thermal resistance $\boldsymbol{R}_{\text{th(j-c)}}$ when the device operates at conduction angles other than d.c.

	ΔZ_{th} (z)	
θ°	sine.	rect.	θ°
180	4.15	2.72	180
120	4.90	4.02	120
90	5.74	4.79	90
60	6.53	5.65	60
30	7.16	6.64	30
15	7.46	7.18	15

Anode Side Cooling				Cathode Sided Cooling			
	$\Delta Z_{th}(z)$				ΔZ_{ti}	(z)	
θ°	sine.	rect.		θ°	sine.	rect.	
180	4.15	2.72		180	4.13	2.71	
120	4.89	4.02		120	4.87	4.00	
90	5.73	4.78		90	5.69	4.76	
60	6.52	5.65		60	6.46	5.60	
30	7.15	6.62		30	7.07	6.56	
15	7.44	7 16	ĺ	15	7 36	7.00	

Fig.9 Maximum (limit) transient thermal impedance - junction to case (°C/kW)



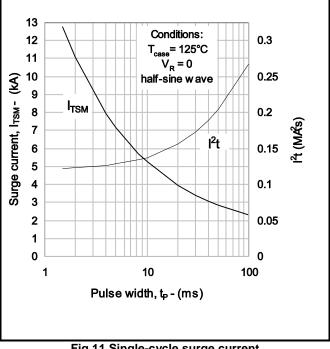


Fig.10 Multi-cycle surge current

Fig.11 Single-cycle surge current

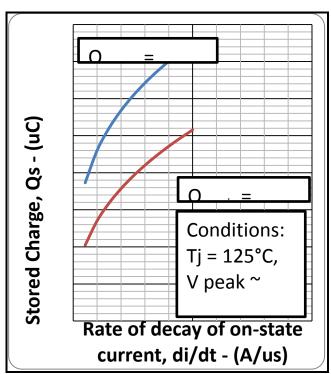


Fig.12 Stored charge

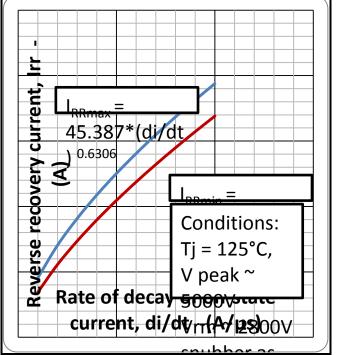


Fig.13 Reverse recovery current

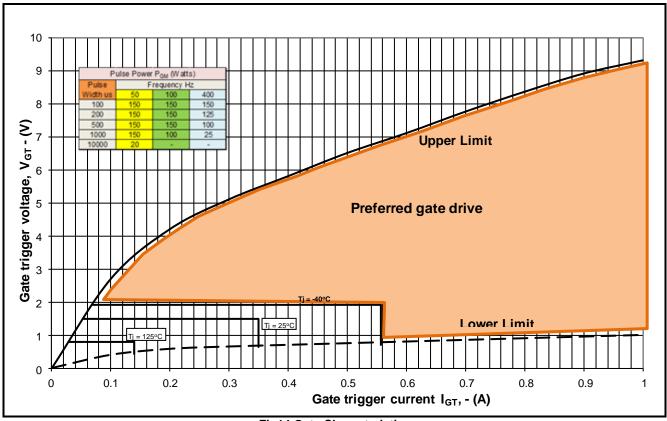


Fig14 Gate Characteristics

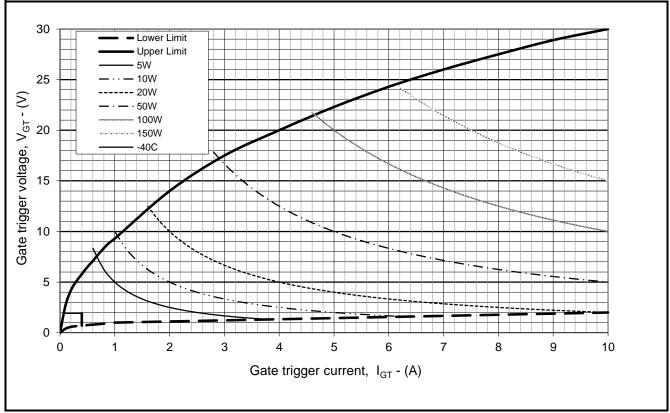


Fig. 15 Gate characteristics



PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

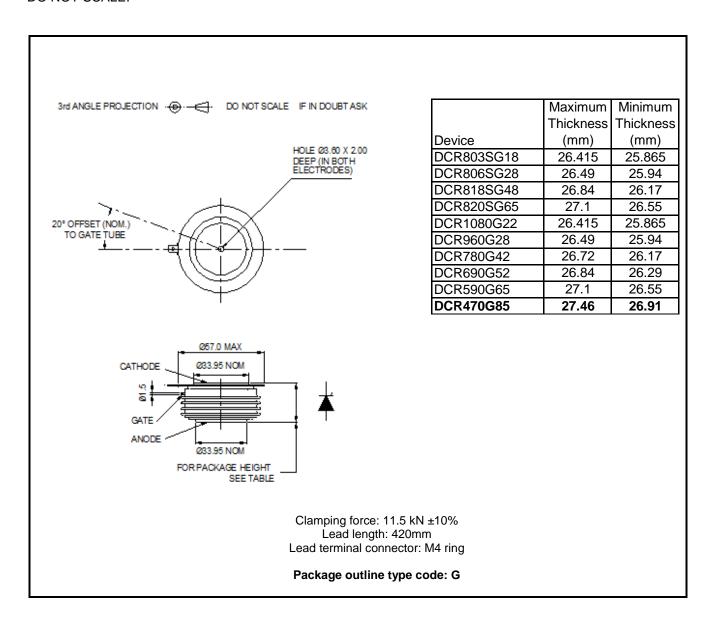


Fig.16 Package outline





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HEADQUARTERS OPERATIONS

DYNEX SEMICONDUCTOR LIMITED
Doddington Road, Lincoln, Lincolnshire, LN6 3LF

United Kingdom.

No Annotation:

Phone: +44 (0) 1522 500500 Fax: +44 (0) 1522 500550 Web: http://www.dynexsemi.com

CUSTOMER SERVICE

Phone: +44 (0) 1522 502753 / 502901 Fax: +44 (0) 1522 500020

e-mail: power_solutions@dynexsemi.com

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